

# Durimide® 7300 Photosensitive Polyimide Precursor

- Copper compatible polyimide
- Designed with a unique structure and sensitizer that gives it the following characteristics:

Enhanced resolution
Wide process latitude
Self priming
Excellent adhesion

- Superior mechanical property retention after extended pressure cooker test
- Cured film thickness range: 3.5-50µm

<u>Type</u>	<u>Viscosity</u>	Cured Film Thickness
Durimide® 7310	3300CS	4-15µm
Durimide® 7320	6400CS	11-25+µm

#### **Compatible Ancillary Products:**

<u>Developer/Rinse Combinations</u>: <u>Back Side Rinse</u>: QZ3501/QZ3512 QZ3501 HTRD2/RER600 HTRD2

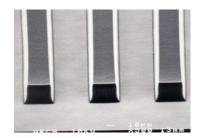
Edge Bead Remover : Stripper Products:

HTRD2 N-Methyl 2-Pyrrolidone

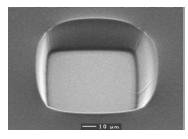
RER470 QZ 3322

#### Cured Film Properties of Durimide® 7300 Series

Tensile Strength	MPa	215
Young's Modulus	GPa	2.5
Tensile Elongation	%	85
Glass Transition Temperature	°C	285
Thermal Decomposition Temperature	°C	525
Coefficient of Thermal Expansion	ppm/°C	55
Dielectric Constant		3.2-3.3
Moisture Absorption@50% RH	%	1.08



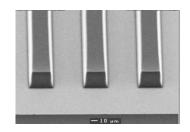
40 µm line/spaces



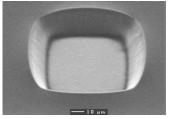
60 µm via

Top view: 1.0µm sputtered Copper, Cured Film Thickness ~ 19µm, E: 150mJ/cm2, broadband exposure

Bottom view: Electroplated Copper, Cured Film Thickness ~ 20µm, E: 150mJ/cm2, broadband exposure



40 µm line/spaces



60 µm via

#### **Process Window**

**Exp.Range** 130-340 mJ/cm2 **Focus Range** 4-10 microns into film

Substrate: Silicon

Soft Bake: 100°C /3mins

PI Thickness: 12µm

**Exposure Tool:** GCA i-line stepper

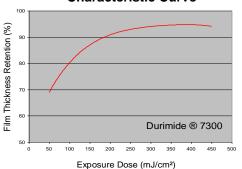
0.35NA, 0.68 sigma

**Post Exposure delay:** 20-22°C/ 30 mins **Developer/Rinse:** HTRD2/RER600

30"/10"/15"

**Cure:** 350°C/ 60 mins

#### **Characteristic Curve**



**Process Summary** 

Substrate: silicon

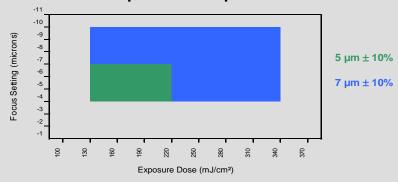
Soft Bake: 100°C /3mins

Polyimide Thickness: 15 µm

Exposure Tool: GCA i-line stepper Post Exposure delay: 20-22°C/30mins Developer/Rinse: HTRD2/RER600

35"/10"/15"

## Process Window for a 5 & 7 μm CD space in a 12 μm film



# Cured Film Thickness vs. Spin Speed Durinide® 7320 Durinide® 7310 Durinide® 7310

Durimide® 7300 undergoes a 45% shrinkage from softbake to cure.

Spin Speed (rpm)

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